[0037] What is claimed is:

1. A package suitable to contain a semiconductor die, the package comprising:

at least one solder-ball at an underside of said package; and

at least one external lead at a side edge of said package.

2. The package of claim 1, wherein said external lead is a surface mount lead of type J-lead.

3. The package of claim 1, wherein said external lead is a surface mount lead of type Gull-wing.

4. The package of claim 1, wherein said external lead is a through-hole lead.

5. The package of claim 1, wherein once said external lead is soldered to a printed circuit board, said external lead is to absorb part of a strain between said package and said printed circuit board, wherein said strain is one of the following: a thermal strain, a mechanical strain, and a thermomechanical strain.

6. A device comprising:

a semiconductor die; and

a package containing said semiconductor die, said package including at least:

at least one solder-ball at an underside of said package; and

at least one external lead at a side edge of said package.

7. The device of claim 6, wherein said external lead is electrically coupled to one or more pads of said semiconductor die.

8. The device of claim 7, wherein said one or more pads are ground terminals of circuitry in said semiconductor die.

9. The device of claim 7, wherein said one or more pads are power supply terminals of circuitry in said semiconductor die.

10. The device of claim 7, wherein said one or more pads are to carry signals of circuitry in said semiconductor die.

11. The device of claim 7, wherein said external lead is a surface mount lead of type J-lead.

12. The device of claim 7, wherein said external lead is a surface mount lead of type Gull-wing.

13. The device of claim 7, wherein said external lead is a through-hole lead.

14. A printed circuit board comprising:

pads suitable to be soldered to solder-balls of a package; and

pads suitable to be soldered to external leads of said package.

15. The printed circuit board of claim 14, wherein at least one of said external leads is a surface mount lead of type J-lead.

16. The printed circuit board of claim 14, wherein at least one of said external leads is a surface mount lead of type Gull-wing.

17. The printed circuit board of claim 14, wherein at least one of said pads has a hole therein.

18. A printed circuit board having a device installed thereon, the printed circuit board comprising:

pads soldered to solder-balls of a package of said device; and

pads soldered to external leads of said package,

wherein said printed circuit board has a voltage monitor installed thereon.

19. The printed circuit board of claim 18, wherein at least one of said external leads is a surface mount lead of type J-lead.

20. The printed circuit board of claim 18, wherein at least one of said external leads is a surface mount lead of type Gull-wing.

21. The printed circuit board of claim 18, wherein at least one of said pads has a hole therein.

22. The printed circuit board of claim 18, wherein said printed circuit board is a motherboard.

23. An apparatus comprising:

an audio input device; and

a printed circuit board having a device installed thereon, said printed circuit board including at least:

pads soldered to solder-balls of a package of said device; and

pads soldered to external leads of said package.

24. The apparatus of claim 23, wherein at least one of said external leads is a surface mount lead of type J-lead.

25. The apparatus of claim 23, wherein at least one of said external leads is a surface mount lead of type Gull-wing.

26. The apparatus of claim 23, wherein at least one of said pads has a hole therein.

27. The apparatus of claim 23, wherein said apparatus is a computer.